

KAA-3528SURKSYKC

HYPER RED

SUPER BRIGHT YELLOW

Features

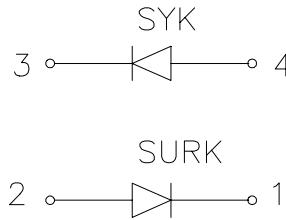
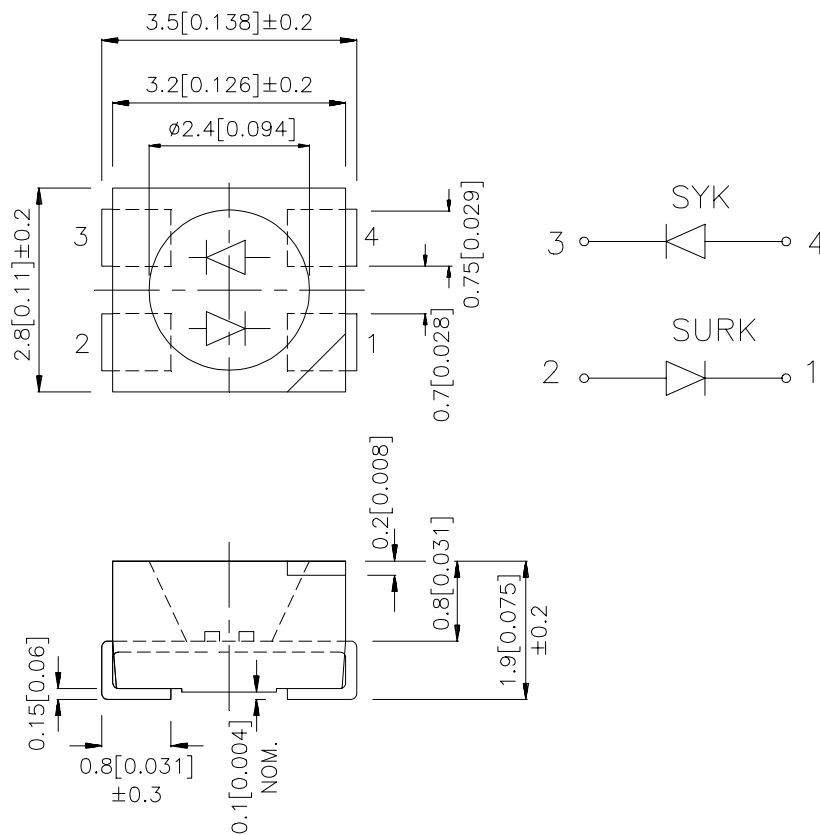
- BOTH CHIPS CAN BE CONTROLLED SEPARATELY.
- SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- AVAILABLE ON TAPE AND REEL.
- PACKAGE: 1500PCS/ REEL.

Description

The Hyper Red source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

The Super Bright Yellow source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
3. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20 mA		Viewing Angle
			Min.	Typ.	2θ1/2
KAA-3528SURKSYKC	HYPER RED (InGaAlP)	WATER CLEAR	70	200	120°
	SUPER BRIGHT YELLOW(InGaAlP)		18	100	

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical / Optical Characteristics at T_A=25°C

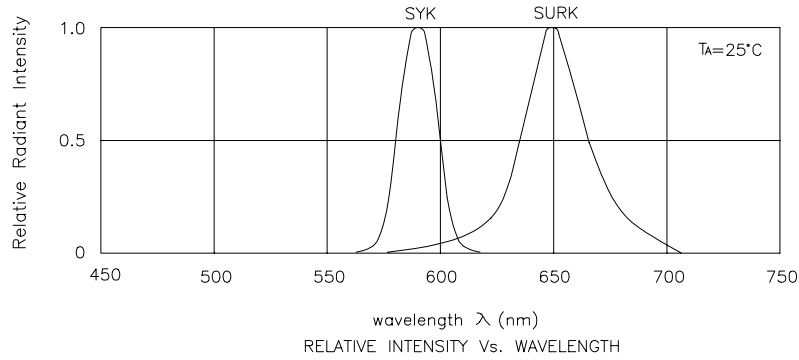
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ _{peak}	Peak Wavelength	Hyper Red Super Bright Yellow	650 590		nm	I _F =20mA
λ _D	Dominate Wavelength	Hyper Red Super Bright Yellow	635 590		nm	I _F =20mA
Δλ _{1/2}	Spectral Line Half-width	Hyper Red Super Bright Yellow	28 20		nm	I _F =20mA
C	Capacitance	Hyper Red Super Bright Yellow	35 20		pF	V _F =0V;f=1 MHz
V _F	Forward Voltage	Hyper Red Super Bright Yellow	1.95 2.0	2.5 2.5	V	I _F =20mA
I _R	Reverse Current	All		10	μA	V _R = 5V

Absolute Maximum Ratings at T_A=25°C

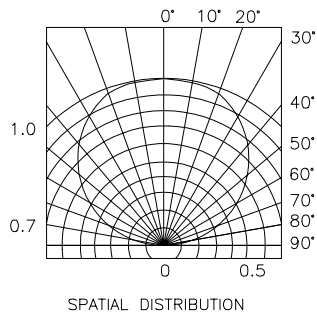
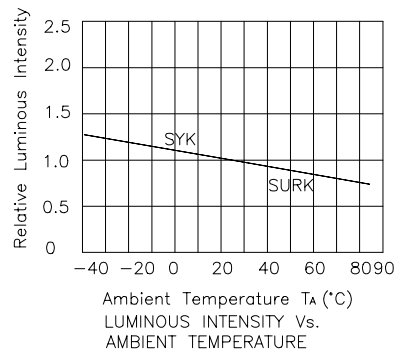
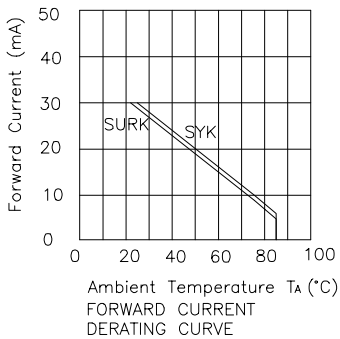
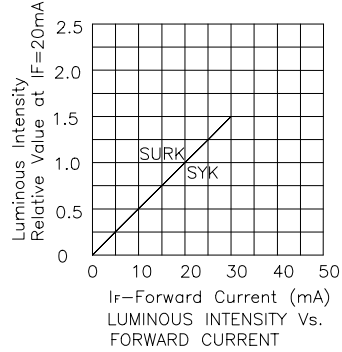
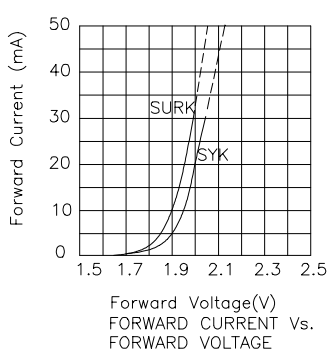
Parameter	Hyper Red	Super Bright Yellow	Units
Power dissipation	170	125	mW
DC Forward Current	30	30	mA
Peak Forward Current [1]	185	175	mA
Reverse Voltage	5	5	V
Operating/Storage Temperature	-40°C To +85°C		

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



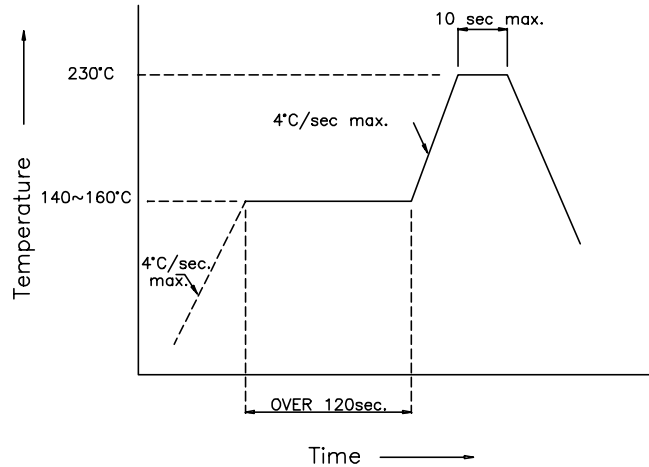
Hyper Red / Super Bright Yellow KAA-3528SURKSYKC



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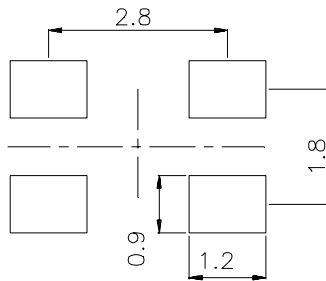
SMT Reflow Soldering Instruction

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern

(Units : mm)



Tape Specifications

(Units : mm)

